

### AMENDMENTS TO THE SPECIFICATION

The following amendments to the specification merely correct minor typographical errors. Specifically the amendments are intended to ensure correspondence between the written text and the provided figures, as noted by the Examiner.

Please amend [0028] as follows:

[0028] As shown in FIG. ~~[[3]]~~ 1, the device 110 is attached to a lead 118 by way of a lead connector 120 adapted to receive one or more electrical leads, such as the illustrated lead 118. The lead connector 120 acts to physically secure the lead 118 to the device 110, and facilitates electrical connection between a conductor in the lead 118 coupling a seed electrode according to the invention to circuitry within the device 110. The lead connector 120 accomplishes this in a substantially fluid-tight environment with biocompatible materials.

Please amend [0032] as follows:

[0032] FIGURE 2 is a block diagram illustrating how the implantable neurostimulator device 110 (FIG. 1) is coupled to two interface modules in the disclosed embodiment of the invention. As illustrated in FIGURE 1, the device 110 includes a lead connector 120 adapted to receive two multi-conductor leads, although only one lead 118 is illustrated in FIGURE 1. Accordingly, one lead is used to couple a first seed electrode interface ~~[[112]]~~ 212 to device 110. In turn, the first seed electrode interface ~~[[112]]~~ 212 is coupled to four seed electrode assemblies ~~114, 116, 118, and 120~~ 214, 216, 218, and 220. Each of the seed electrode assemblies ~~114-120~~ 214-220 is electrically coupled to the device 110 through the first interface ~~[[112]]~~ 212 as illustrated. Similarly, a second seed electrode interface ~~[[122]]~~ 222 electrically couples four seed electrode assemblies ~~124, 126, 128, and 130~~ 224, 226, 228, and 230 to the device 110. It should be observed that other configurations of the device 110 and one or more interfaces and seed electrode assemblies are possible. In one embodiment of the invention, seed electrode assemblies can be connected directly to the device 110. However, and interface (such as the two interfaces ~~[[112]]~~ 212 and ~~[[122]]~~ 222) interposed between the device 110 and any seed electrodes will allow the device 110 to

be explanted and replaced, or additional seed electrodes added, without the need to disturb existing seed electrode assemblies

Please amend [0041] as follows:

[0041] Accordingly, then, one or more seed electrode assemblies (as in the seed electrode assembly 310 of FIGURE 3) may be coupled to the interface 510; the disclosed embodiment of the interface 510 receives up to four seed electrode assemblies. A single seed electrode assembly 310 (FIGURE 3) is connected to the interface 510 by routing its wire ~~[[514]]~~ 314 through a hole (such as one of the two visible holes 540 and 542) in the housing, positioning the wire ~~[[514]]~~ 314 over a desired and selected punchdown terminal one of the punchdown terminals 530-536), and pressing the wire ~~[[514]]~~ 314 down into the selected punchdown terminal at substantially any location along the length of the wire ~~[[514]]~~ 314. A tool may be provided for the purpose; punchdown terminals and tools are generally understood by practitioners of ordinary skill in the art to which this invention pertains.

Please amend [0042] as follows:

[0042] As is well known, the act of pushing the wire ~~[[514]]~~ 314 down into a punchdown terminal will cause the insulating cover 316 over the wire 314 to be penetrated by the blade of the punchdown terminal, enabling electrical conduction between the blade and the wire 314, and hence a closed electrical circuit between one of the ring terminals 514-520 and the seed electrode 312. If there is any unused length of wire 314 after it is connected to the interface 510, it may be trimmed. It should be apparent that after trimming, different custom lengths of wire 314 may be present, thereby reducing any undesired slack in wires leading up to the seed electrode 312.

Please amend [0047] as follows:

[0047] As illustrated, and consistent with the illustration of FIG. ~~[[5]]~~ 6, the disclosed burr hole cover 610 has a lead body 620 connected to a neurostimulator (such as the device 110, not shown) and accommodates four seed electrode assemblies 622, 624, 626, and 628, which are shown inserted into desired electrode sites. Contrary to the illustration of FIG. 5, this embodiment receives

the lead body 620 at a top location and the seed electrode assemblies 622-628 at a bottom location. Choosing desired electrode sites may be performed at any appropriate stage of the surgical procedure, including presurgically in an operative planning stage; intraoperatively after a craniotomy have been performed or a burr hole has been made; or intraoperatively after one or more other procedures, such as functional mapping, have been performed.